ABSTRACT

INTEGRATED CIRCUIT PACKAGING SYSTEM WITH UNDERFILL AND METHOD OF MANUFACTURE THEREOF

A method of manufacture of an integrated circuit packaging system includes: providing a device having a conductor with ends exposed on opposite sides of the device; forming a first surface depression on the device around the conductor; connecting a first component over the conductor and surrounded by the first surface depression; and applying a first underfill between the first component and the device, the first underfill substantially filled within a perimeter of the first surface depression.

(Figure 1)